ABSTRACT

Provided is a method for manufacturing an electronic component by using a solder joining method for bonding a first electronic component having a metal electrode for connection purposes with a second electronic component having a solder electrode for connection purposes, the method comprising the steps (i) to (iv) in this order: (i) forming a resin layer containing a thermosetting resin on at least one of the solder joint surfaces of said first electronic component and said second electronic component; (ii) positioning, after the formation of said resin layer containing a thermosetting resin, said metal electrode for connection purposes of said first electronic component and said solder electrode for connection purposes of said second electronic component to face each other, heating said positioned electrodes at a temperature lower than the melting point of said solder of said solder electrode for connection purposes and applying pressure, and thereby bringing said metal electrode for connection purposes and said solder electrode for connection purposes into contact; (iii) heating said first electronic component and said second electronic component that have been brought into contact at a temperature higher than the melting point of said solder of said solder electrode for connection purposes while applying pressure using a pressurized fluid, and thereby fusion bonding said solder of said solder electrode for connection purposes to said metal electrode for connection purposes; and (iv) heating said resin layer containing a thermosetting resin at a temperature lower than the melting point of said solder of said solder electrode for connection

purposes, and thereby curing said resin layer.